H L X 20125025 A03

Manufacturer:Beijing Netac Innovation Technology Development Co.,Ltd.

Features

1.Surface Mounted Devices with a small dimension of 2.0 x 1.25 x 0.25 mm^3 meet future miniaturization trend.

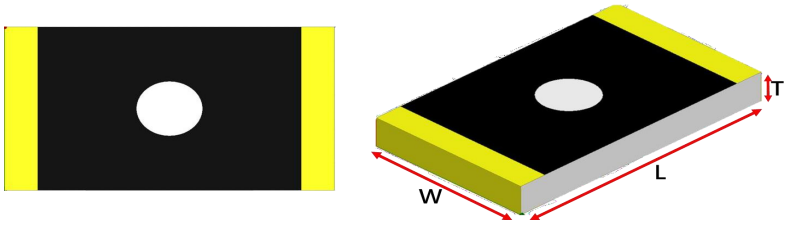
2.Embedded and (Low Temperature Co-fired Ceramic) technology is able to future integratewith system design as well as beautifying the housing of final product.

3. High Stability in Temperature / Humidity Change

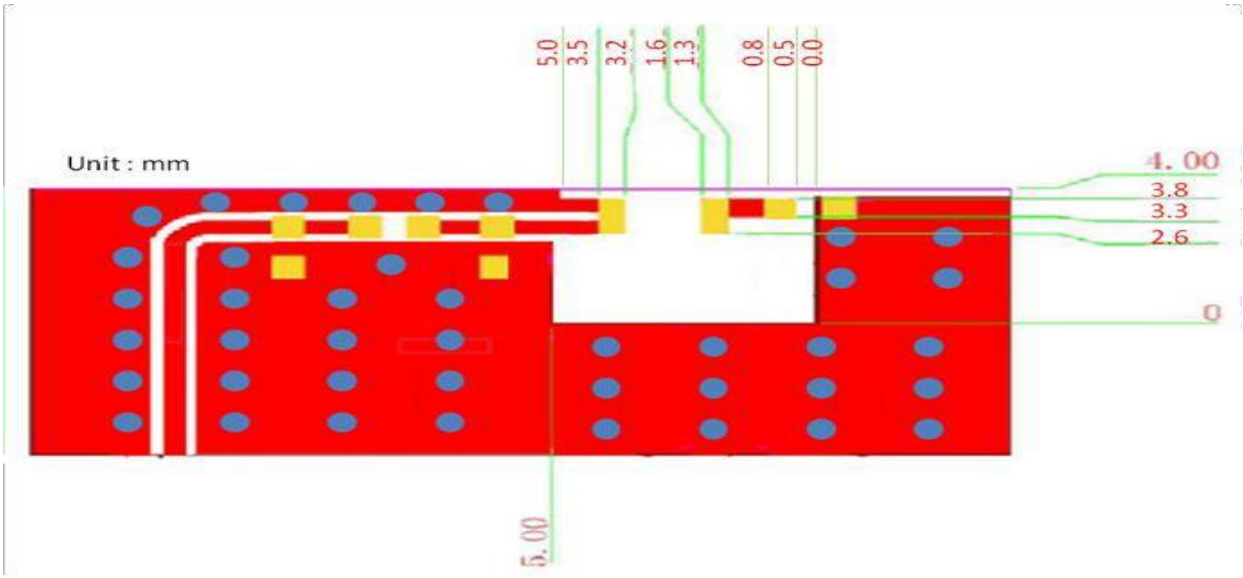
Applications

1. Bluetooth
2. Wireless LAN
3. HormRF
4. ISM band 2.4GHz wireless applications

Dimensions（Unit：mm）

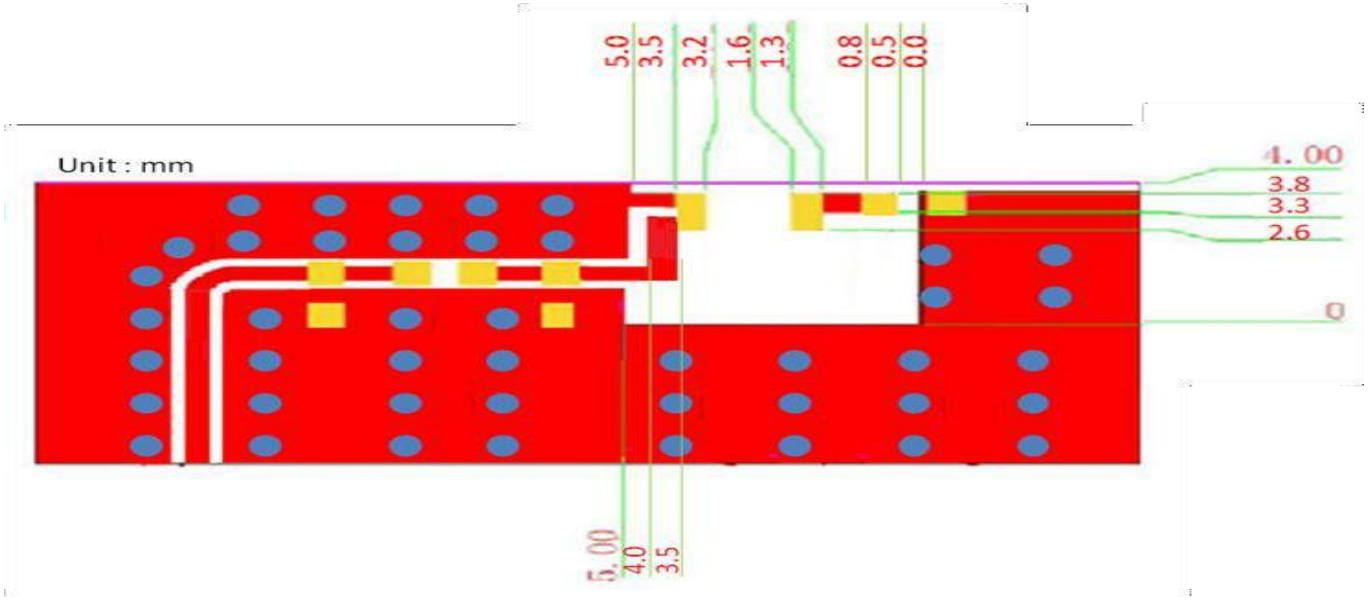


	Dimension (mm)
L	2.0 ± 0.20
W	1.2 ± 0.20
T	0.25 ± 0.05

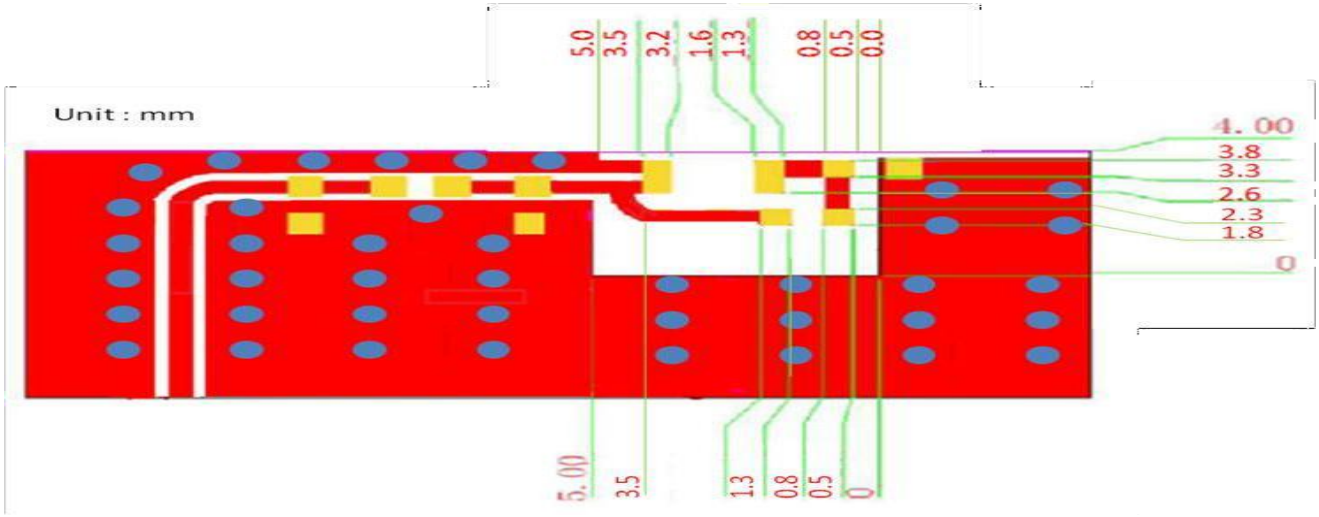


H L X 20125025 A03

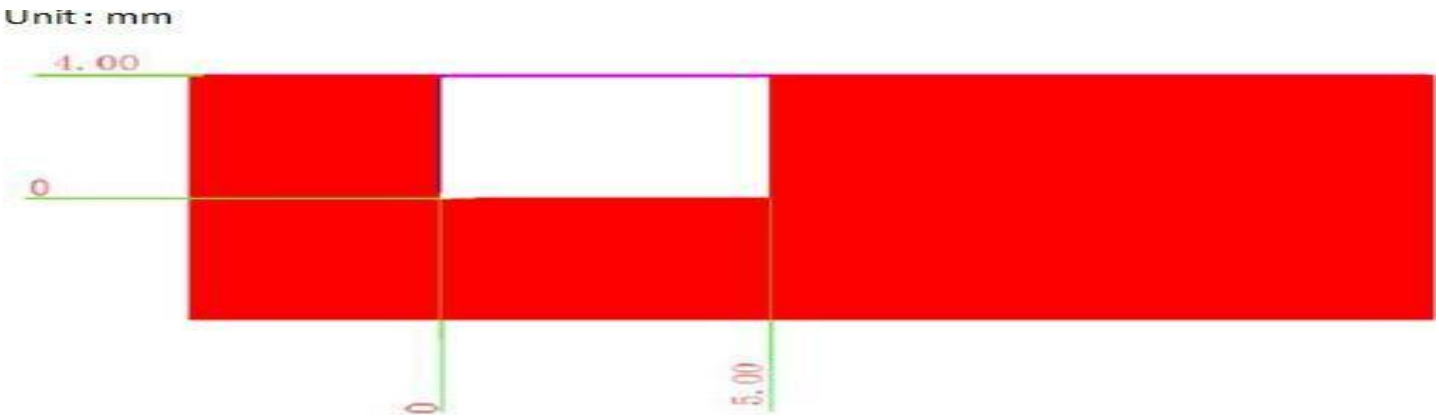
Type2 :



Type3 :

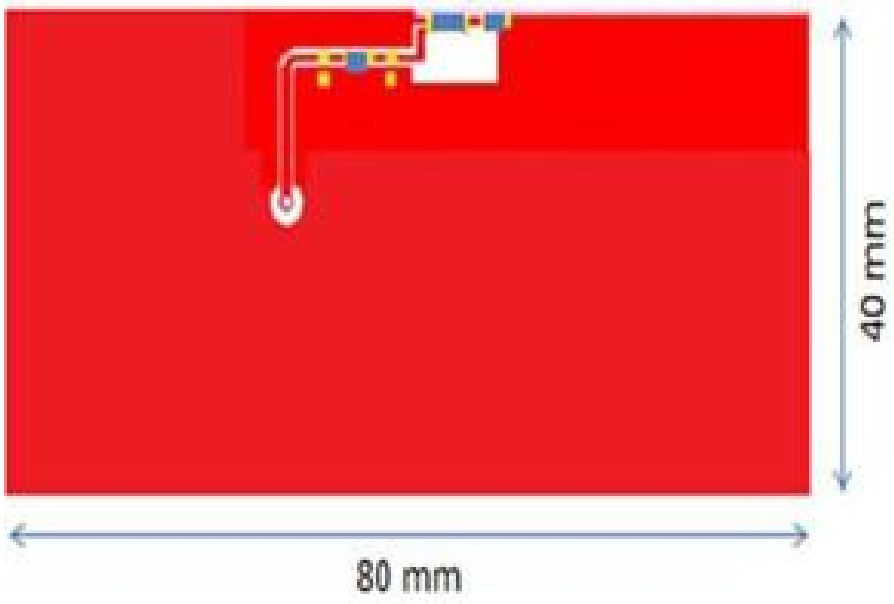


PCB Bottom View :



H L X 20125025 A03

Evaluation Board and Matching Circuits

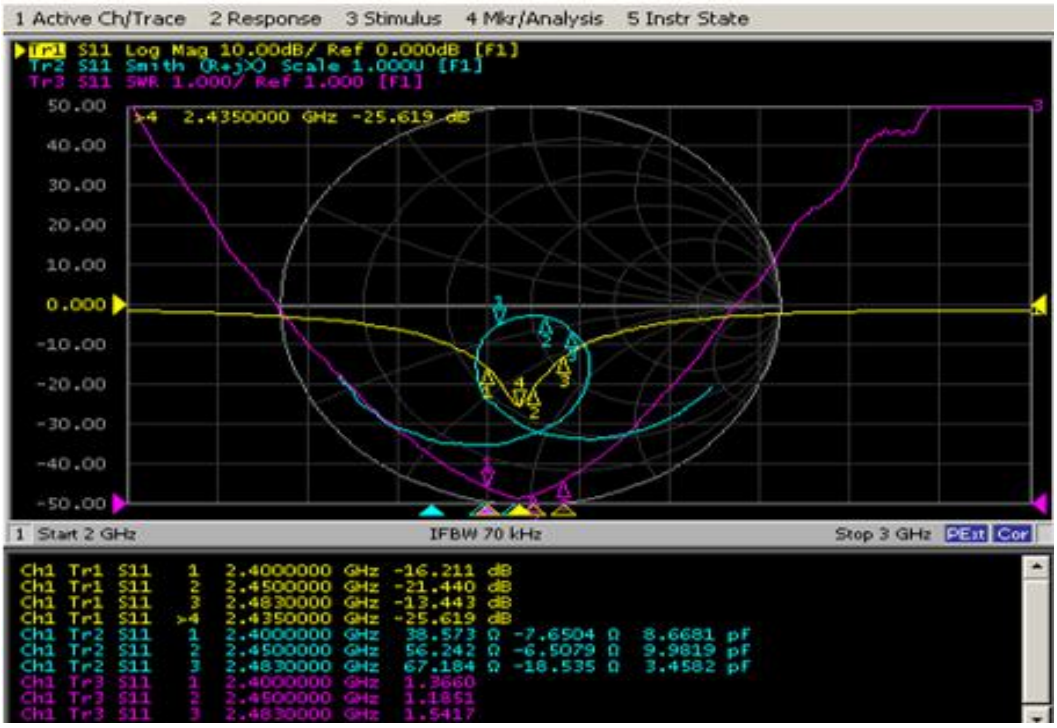


Electrical Characteristics

Specification		
Part Number	ANTD21W02-X1	
Central Frequency	2450	MHz
Bandwidth	90 (Min.)	MHz
Return Loss	-10 (Max)	dB
Peak Gain	2.11	dBi
Impedance	50	Ω
Operating Temperature	-40～+85	℃
Maximum Power	1	W
Resistance to Soldering Heats	10 (@ 260℃)	sec.
Polarization	Linear	
Azimuth Beamwidth	Omni-directional	
Termination	Cu / Sn (Leadless)	

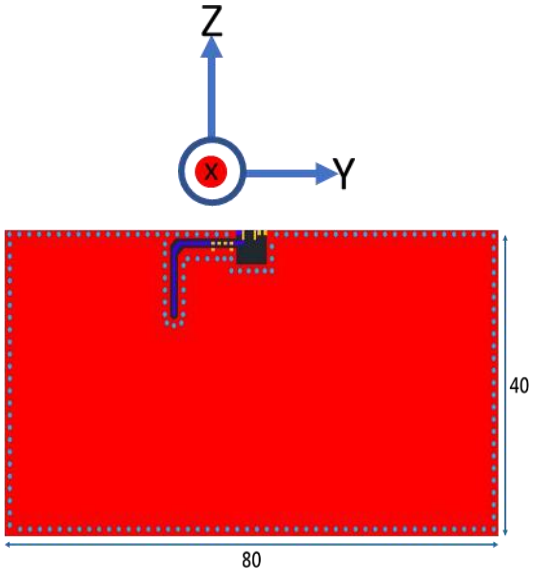
H L X 20125025 A03

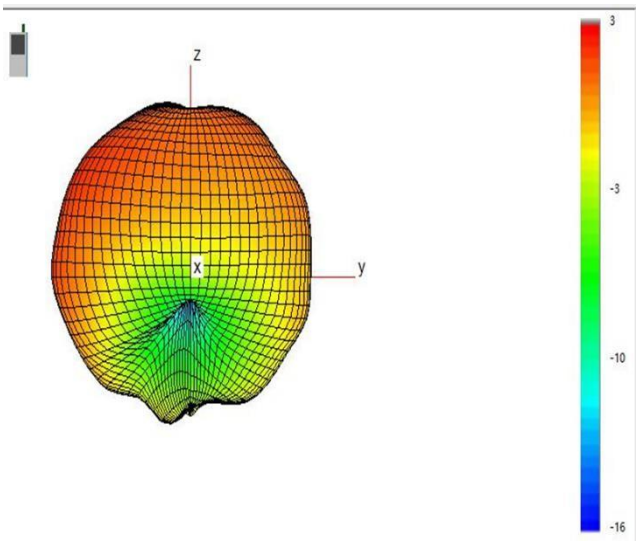
Characteristic curve



Radiation Pattern

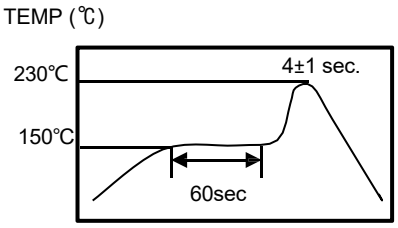
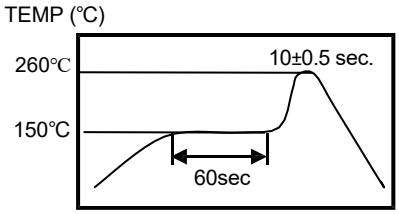
Frequency (MHz)	2400	2450	2500
Efficiency (dB)	-1.42	-1.24	-1.47
Efficiency (%)	71	75	71
Peak Gain (dBi)	2.11	2.06	1.94





HLX20125025A03

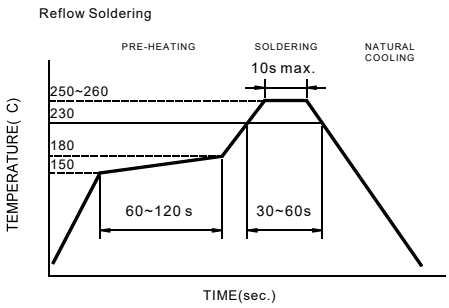
Reliability and Test Condictions

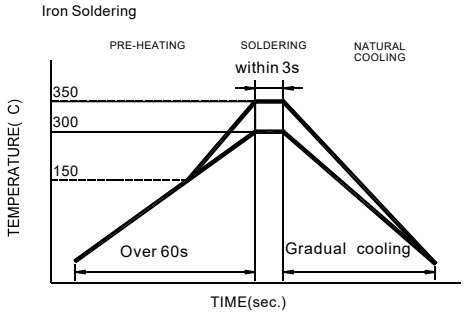
<table>
<tr><th>ITEM</th><th>REQUIREMENTS</th><th>TEST CONDITION</th></tr>
<tr><td>Solderability</td><td>1. Wetting shall exceed 90% coverage
2. No visible mechanical damage
 
</td><td>Pre-heating temperature:150℃/60sec.
Solder temperature:230±5℃
Duration:4±1sec.
Solder:Sn-Ag3.0-Cu0.5
Flux for lead free: rosin</td></tr>
<tr><td>Solder heat Resistance</td><td>1. No visible mechanical damage
2. Central Freq. change :within ± 6%
 
</td><td>Pre-heating temperature:150℃/60sec.
Solder temperature:260±5℃
Duration:10±0.5sec.
Solder:Sn-Ag3.0-Cu0.5
Flux for lead free: rosin</td></tr>
<tr><td>Component Adhesion (Push test)</td><td>1. No visible mechanical damage</td><td>The device should be reflow soldered(230±5℃ for 10sec.) to a tinned copper substrate A dynometer force gauge should be applied the side of the component. The device must with-ST-F 0.5 Kg without failure of the termination attached to component.</td></tr>
<tr><td>Component Adhesion (Pull test)</td><td>1. No visible mechanical damage</td><td>Insert 10cm wire into the remaining open eye bend ,the ends of even wire lengths upward and wind together.
Terminal shall not be remarkably damaged.</td></tr>
<tr><td>Thermal shock</td><td>1. No visible mechanical damage
2. Central Freq. change :within ±6%
<table>
<tr><th>Phase</th><th>Temperature(℃)</th><th>Time(min)</th></tr>
<tr><td>1</td><td>+85±5℃</td><td>30±3</td></tr>
<tr><td>2</td><td>Room Temperature</td><td>Within 3sec</td></tr>
<tr><td>3</td><td>-40±2℃</td><td>30±3</td></tr>
<tr><td>4</td><td>Room Temperature</td><td>Within 3sec</td></tr>
</table></td><td>+85℃=>30±3min
-40℃=>30±3min
Test cycle:10 cycles
The chip shall be stabilized at normal condition for 2~3 hours before measuring.</td></tr>
<tr><td>Resistance to High Temperature</td><td>1. No visible mechanical damage
2. Central Freq. change :within ±6%
3. No disconnection or short circuit.</td><td>Temperature: 85±5℃
Duration: 1000±12hrs
The chip shall be stabilized at normal condition for 2~3 hours before measuring.</td></tr>
<tr><td>Resistance to Low Temperature</td><td>1. No visible mechanical damage
2. Central Freq. change :within ±6%
3. No disconnection or short circuit.</td><td>Temperature:-40±5℃
Duration: 1000±12hrs
The chip shall be stabilized at normal condition for 2~3 hours before measuring.</td></tr>
<tr><td>Humidity</td><td>1. No visible mechanical damage
2. Central Freq. change :within ±6%
3. No disconnection or short circuit.</td><td>Temperature: 40±2℃
Humidity: 90% to 95% RH
Duration: 1000±12hrs
The chip shall be stabilized at normal condition for 2~3 hours before measuring.</td></tr>
</table>

H L X 20125025 A03

Soldering and Mounting

Mildly activated rosin fluxes are preferred. The minimum amount of solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate. The terminations are suitable for all wave and re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.





Recommended temperature profiles for re-flow soldering in Figure 1.

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

·Preheat circuit and products to 150℃

·Never contact the ceramic with the iron tip

·Use a 20 watt soldering iron with tip diameter of 1.0mm

·280℃ tip temperature (max)

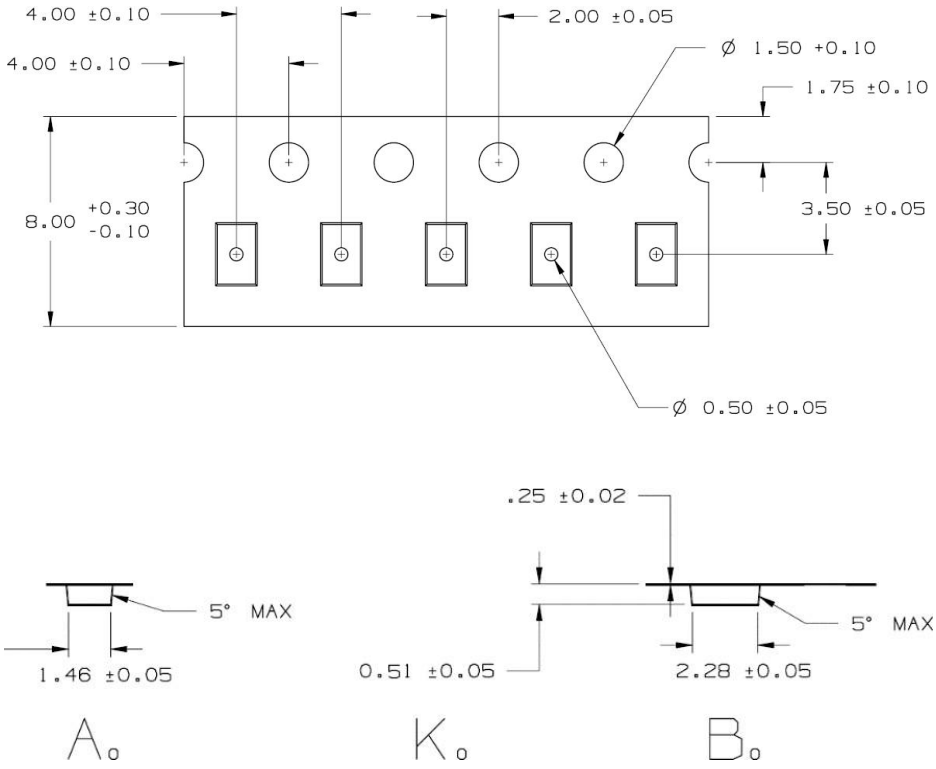
·1.0mm tip diameter (max)

·Limit soldering time to 3 sec.

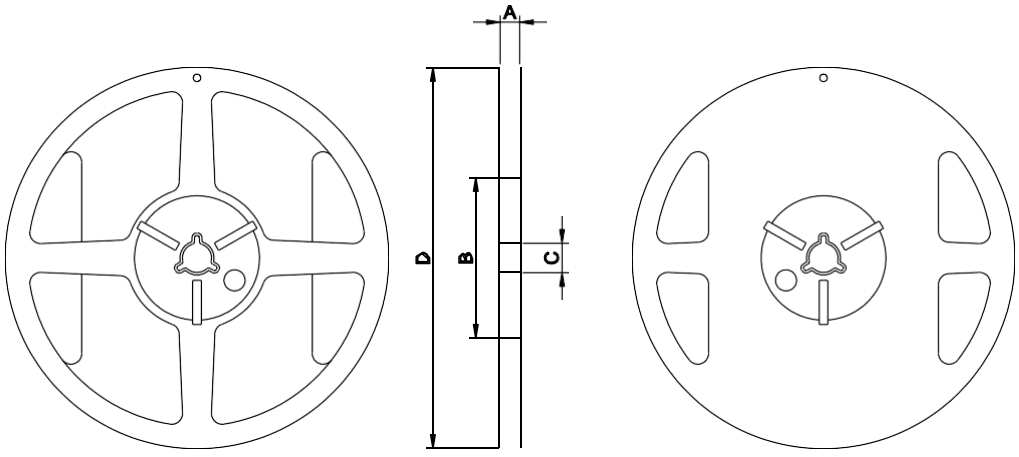
H L X 20125025 A03

Packaging Information

◆Tape Specification:



◆Reel Specification: (7”, Φ180 mm)



7" x 8 mm

Tape Width(mm)	A(mm)	B(mm)	C(mm)	D(mm)	Chip/Reel(pcs)
8	9.0±0.5	60±2	13.5±0.5	178±2	6000

H L X 20125025 A03

Storage and Transportation Information

Storage Conditions

To maintain the solderability of terminal electrodes:

1. Temperature and humidity conditions: -10~ 40℃ and 30~70% RH.
2. Recommended products should be used within 6 months from the time of delivery.
3. The packaging material should be kept where no chlorine or sulfur exists in the air.

Transportation Conditions

1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
3. Bulk handling should ensure that abrasion and mechanical shock are minimized.